

S1A THRU S1M

Features

- For Surface Mount Applications
- Extremely Low Thermal Resistance
- Easy Pick And Place
- High Temp Soldering: 250°C for 10 Seconds At Terminals

1 Amp Silicon Rectifier 50 to 1000 Volts

Maximum Ratings

- Operating Temperature: -65°C to +175°C
- Storage Temperature: -65°C to +175°C
- Maximum Thermal Resistance; 15°C/W Junction To Lead

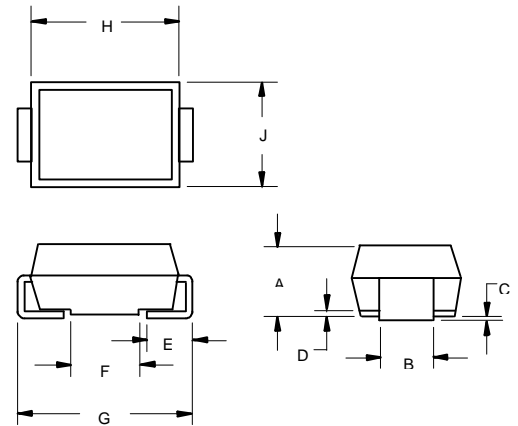
Microsemi Catalog Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
SMB4001	S1A	50V	35V	50V
SMB4002	S1B	100V	70V	100V
SMB4003	S1D	200V	140V	200V
SMB4004	S1G	400V	280V	400V
SMB4005	S1J	600V	420V	600V
SMB4006	S1K	800V	560V	800V
SMB4007	S1M	1000V	700V	1000V

Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward current	$I_{F(AV)}$	1.0A	$T_J = 75^\circ\text{C}$
Peak Forward Surge Current	I_{FSM}	50A	8.3ms, half sine, $T_J = 150^\circ\text{C}$
Maximum Instantaneous Forward Voltage	V_F	1.1V	$I_{FM} = 1.0A$; $T_J = 25^\circ\text{C}^*$
Maximum DC Reverse Current At Rated DC Blocking Voltage	I_R	10µA 50µA	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$
Maximum Reverse Recovery Time	T_{rr}	1.8µs	$I_F=0.5A$, $I_R=1.0A$, $I_{rr}=0.25A$
Typical Junction Capacitance	C_J	15pF	Measured at 1.0MHz, $V_R=4.0V$

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

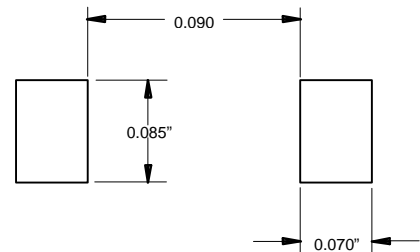
DO-214AA (SMBJ)



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.075	.115	1.90	2.92	1
B	.081	.087	2.06	2.21	
C	.004	.008	.10	.20	
D	---	.02	---	.51	
E	.030	.060	.76	1.52	
F	.065	.084	1.65	2.13	
G	.205	.220	5.21	5.59	
H	.160	.180	4.06	4.57	
J	.130	.155	3.30	3.94	

1) Maximum Jeduc Spec is .096" or 2.44 MM

SUGGESTED SOLDER PAD LAYOUT



S1A thru S1M

Figure 1
Typical Forward Characteristics

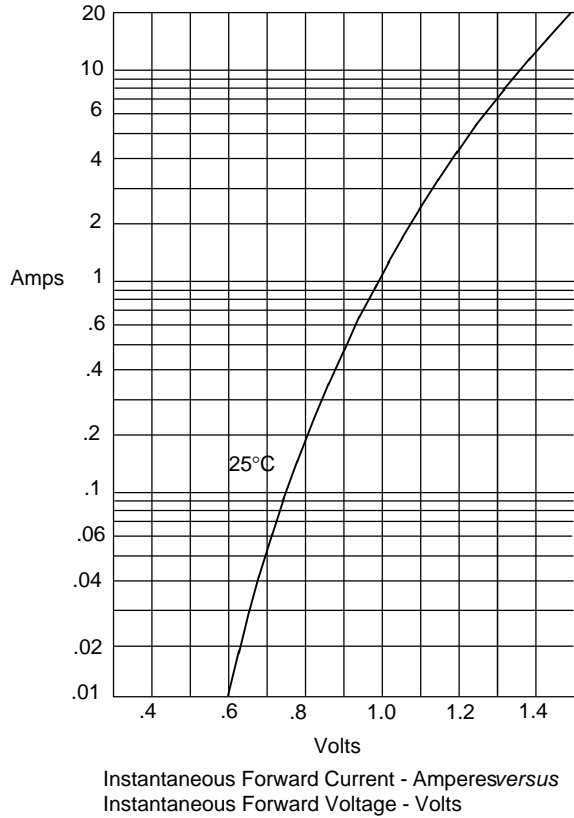


Figure 3
Maximum Overload Surge Current

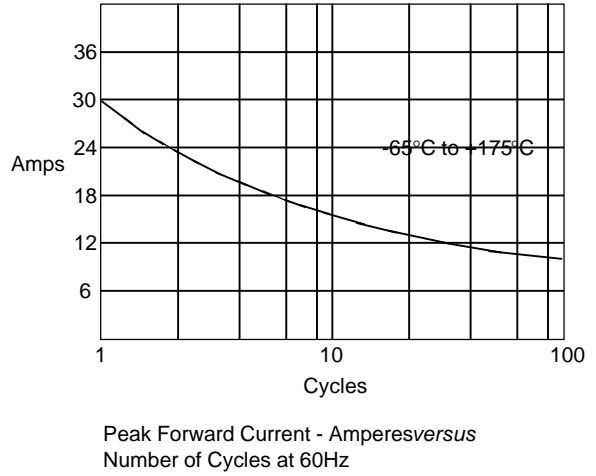


Figure 4
Forward Derating Curve

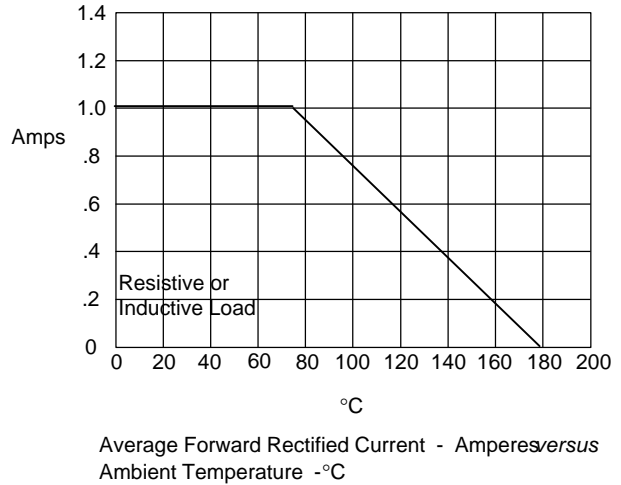
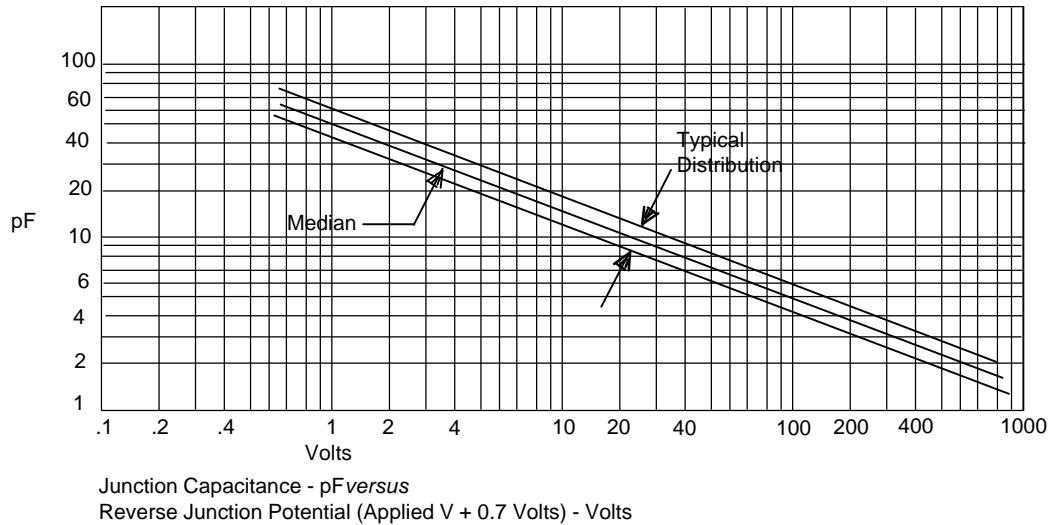
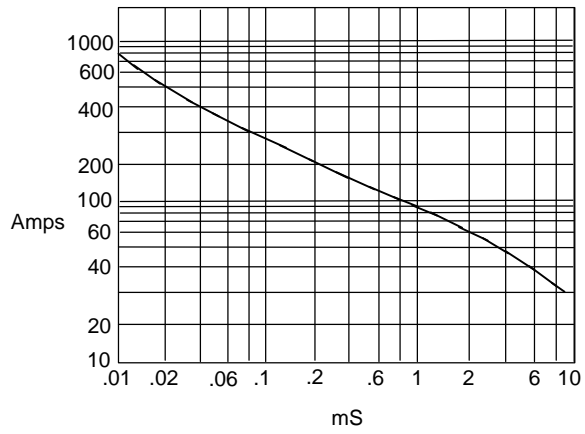


Figure 2
Junction Capacitance



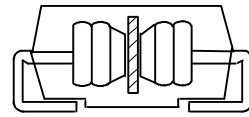
S1A thru S1M

Figure 5
Peak Forward Surge Current



Peak Forward Surge Current - Amperes *versus*
Pulse Duration - Milliseconds (mS)

Figure 6
New SMB Assembly



Round Lead
Process